

Title (en)

Substrate processing apparatus and substrate inspection method

Title (de)

Substrat-Verarbeitungsvorrichtung und Substrat-Inspektionsverfahren

Title (fr)

Dispositif de traitement de substrat et procédé d'inspection de substrat

Publication

**EP 1184895 A2 20020306 (EN)**

Application

**EP 01121029 A 20010831**

Priority

- JP 2000265318 A 20000901
- JP 2001209088 A 20010710

Abstract (en)

An inspection unit is provided in a substrate processing apparatus performing resist coating processing and development processing on a substrate. In the inspection unit, a film thickness measuring device, a line width measuring device, an overlay measuring device and a macro defect inspection device are successively stacked and arranged from below. The inspection unit is provided on an intermediate portion of a substrate transport path formed in the substrate processing apparatus. The substrate processed in the substrate processing apparatus is selectively introduced into each inspection part. Therefore, the apparatus can properly inspect the substrate at need while suppressing reduction of the throughput. Thus provided are a substrate processing apparatus and a substrate inspection method capable of properly inspecting a substrate while suppressing reduction of the throughput.

IPC 1-7

**H01L 21/00**

IPC 8 full level

**G03F 7/16** (2006.01); **H01L 21/67** (2006.01); **B05C 11/00** (2006.01); **B05D 1/40** (2006.01); **B05D 7/00** (2006.01); **G03F 7/30** (2006.01); **H01L 21/00** (2006.01); **H01L 21/027** (2006.01); **H01L 21/677** (2006.01)

CPC (source: EP US)

**H01L 21/67207** (2013.01 - EP US); **H01L 21/67253** (2013.01 - EP US)

Cited by

JP2008506145A; FR2872502A1; WO2006013257A1

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

**EP 1184895 A2 20020306**; **EP 1184895 A3 20060125**; **EP 1184895 B1 20131218**; JP 2002151403 A 20020524; JP 4004248 B2 20071107; US 2002189758 A1 20021219; US 6790287 B2 20040914

DOCDB simple family (application)

**EP 01121029 A 20010831**; JP 2001209088 A 20010710; US 94215301 A 20010829